



**PATENT APPLICATION**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q62228

Yoshihisa FURUTA, et al.

Appln. No.: 09/719,422

Group Art Unit: 1733

Confirmation No.: 7788

Examiner: Barbara J. MUSSER

Filed: December 12, 2000

For: METHOD OF RESIN ENCAPSULATING SEMICONDUCTOR CHIP AND  
PRESSURE-SENSITIVE ADHESIVE TAPE FOR ADHESION TO LEADFRAME  
AND THE LIKE

**RECEIVED**  
FEB 19 2003  
TC 1700

**SUBMISSION OF DRAWINGS**

Commissioner for Patents  
Washington, D.C. 20231

Sir:

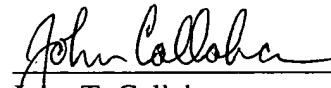
Submitted herewith please find 1 sheet of drawing in compliance with 37 C.F.R. § 1.84.

The Examiner is respectfully requested to acknowledge receipt of this drawing.

The submitted drawing incorporates the proposed drawing changes approved in Paper  
No. 9.

Respectfully submitted,

SUGHRUE MION, PLLC  
Telephone: (202) 293-7060  
Facsimile: (202) 293-7860

  
John T. Callahan  
Registration No. 32,607

WASHINGTON OFFICE



**23373**

PATENT TRADEMARK OFFICE

Date: February 12, 2003